Sheet 1 of 1...

Form 1449*

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INFORMATION DISCLOSURE STATEMENT BY APPLICANT

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Applicant: Jonathan McFarland et al.

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U.S. PATENT DOCUMENTS

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*Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate	
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$\frac{1}{2}$ Illa	h					((
V MIIM	Z 5,136,359	08/04/1992	Takayama, Y., et al.	357	65	12/19/90	
	_ 5,188,702	02/23/1993	Takayama, Y., et al.	156	630	04/23/92	
	_ 5,262,226	11/16/1993	Yoshida, Y.	428	209	03/04/91	
	_ 5,502,891	04/02/1996	Mori, H., et al.	29	840	07/05/94	
	_ 5,604,379	02/18/1997	Mori, K., et al.	257	738	05/30/95	
	_ 5,679,493	10/21/1997	Kai, T.	430	126	10/02/95	
	_ 5,681,647	10/28/1997	Caillat, P.	428	209	10/03/95	
	_ 5,770,305	06/23/1998	Terasaka, S.	428	328	09/27/95	
	_ 5,879,530	03/09/1999	Caillat, P.	205	122	05/29/97	
	_ 6,031,590	02/29/2000	Kim, S.J.	349	86	01/21/98	
		FC	REIGN PATENT DOCUMENTS				
**Examiner Initial	Document Number	Date	Country	Class	Subclass	Translation Yes No	
THILIGH	DOCUMENT NUMBER	Date	country	CIGSS	Smcrass	169 MO	

**Examiner						Translation	
Initial	Document Number	Date	Country	Class	Subclass	Yes No	

OTHER DOCUMENTS

(Including Author, Title, Date, Pertinent Pages, Etc.)

Delaney, D., et al., "Flip Chip Assembly Utilizing Anisotropic Conductive Films: A Feasibility Study", 2000 Electronic Components and Technology Conference, 641-645, (2000)

Examiner

Date Considered